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United States Patent [19]

Oba et al.

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[45] **Date of Patent: ** Oct. 24, 2000**

[54] **SEMICONDUCTOR ELEMENT**

[75] Inventors: **Haruo Oba; Yoshio Kondo**, both of Tokyo, Japan

[73] Assignee: **Sony Corporation**, Japan

[**] Term: **14 Years**

[21] Appl. No.: **29/115,446**

[22] Filed: **Dec. 15, 1999**

D. 376,133	12/1996	Kerklaan	D13/182
D. 379,350	5/1997	Kerklaan	D13/182
D. 386,475	11/1997	Hiramatsu	D13/182
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Publication; "PowerShot"; Digital Camera; Cannon; Mar. 1997.

Publication; "Picona", NEC; Mar. 1997; PC-FH045 and PC-FH155.

Primary Examiner—Brian N. Vinson
Attorney, Agent, or Firm—Rader, Fishman & Grauer

Related U.S. Application Data

[62] Division of application No. 29/083,237, Feb. 6, 1998, Pat. No. Des. 421,967.

[30] Foreign Application Priority Data

Aug. 6, 1997 [JP] Japan 9-64173

[51] **LOC (7) Cl.** **13-03**

[52] **U.S. Cl.** **D13/182**

[58] **Field of Search** D13/182, 105, D13/107, 114, 117; 174/521; 361/579, 728, 736, 737, 742, 752, 802; 439/328, 377

[57] CLAIM

The ornamental design for a semiconductor element, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a semiconductor element showing our new design;
FIG. 2 is a top plan view thereof;
FIG. 3 is a left side elevational view thereof;
FIG. 4 is a front elevational view thereof;
FIG. 5 is a bottom plan view thereof;
FIG. 6 is a right side elevational view thereof; and,
FIG. 7 is a rear elevational view thereof.

[56] References Cited

U.S. PATENT DOCUMENTS

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D. 358,806	5/1995	Siegel et al.	D13/182
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1 Claim, 4 Drawing Sheets

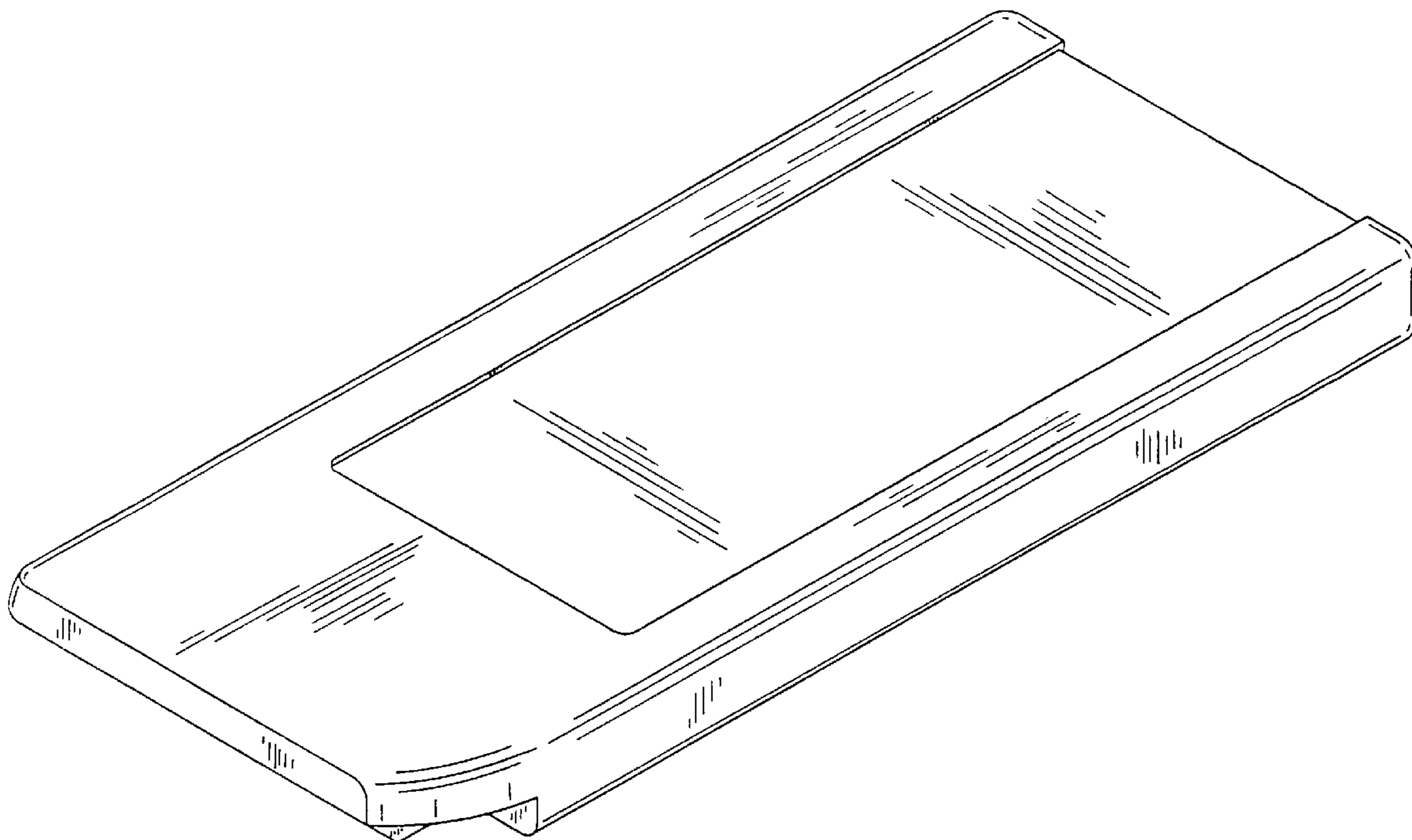


FIG. 1

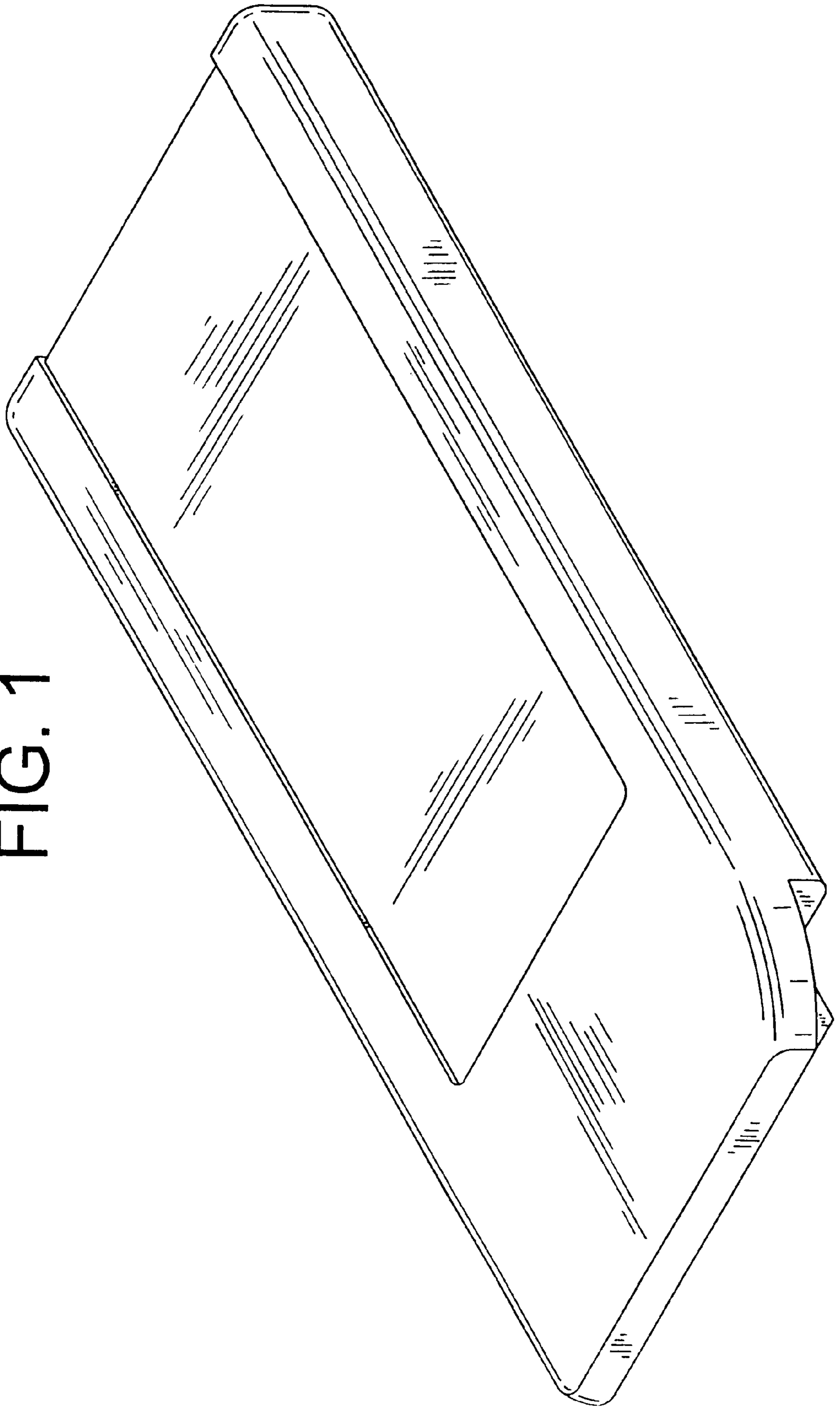


FIG. 2

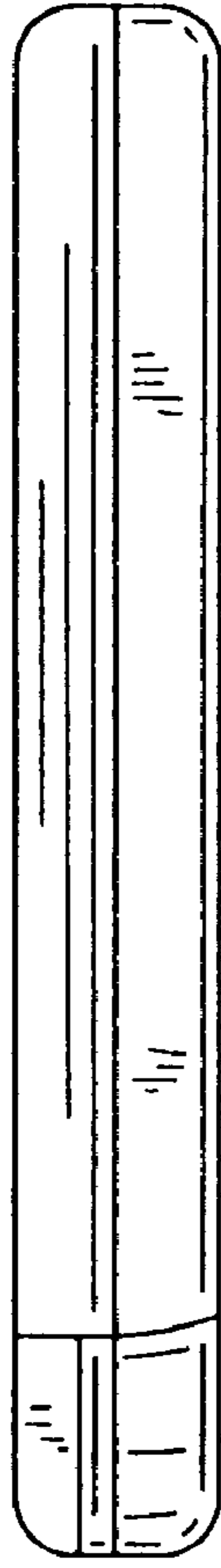


FIG. 5

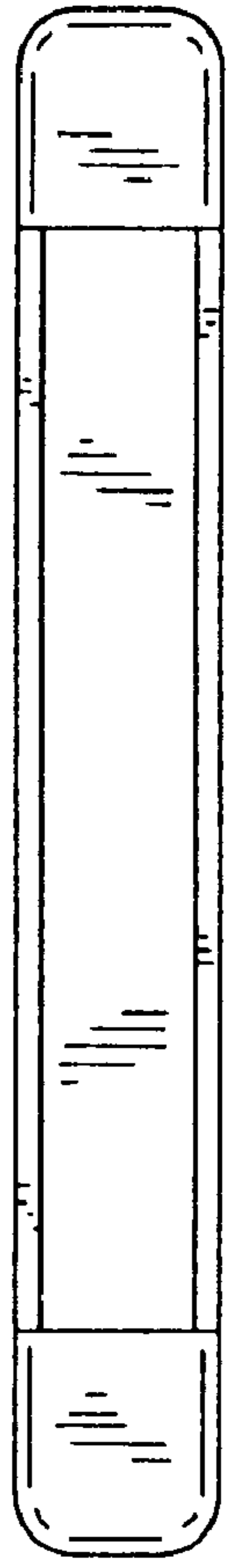


FIG. 3

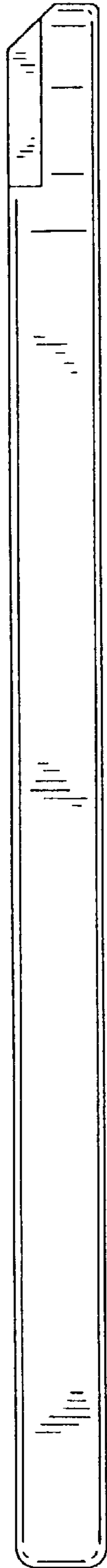


FIG. 4

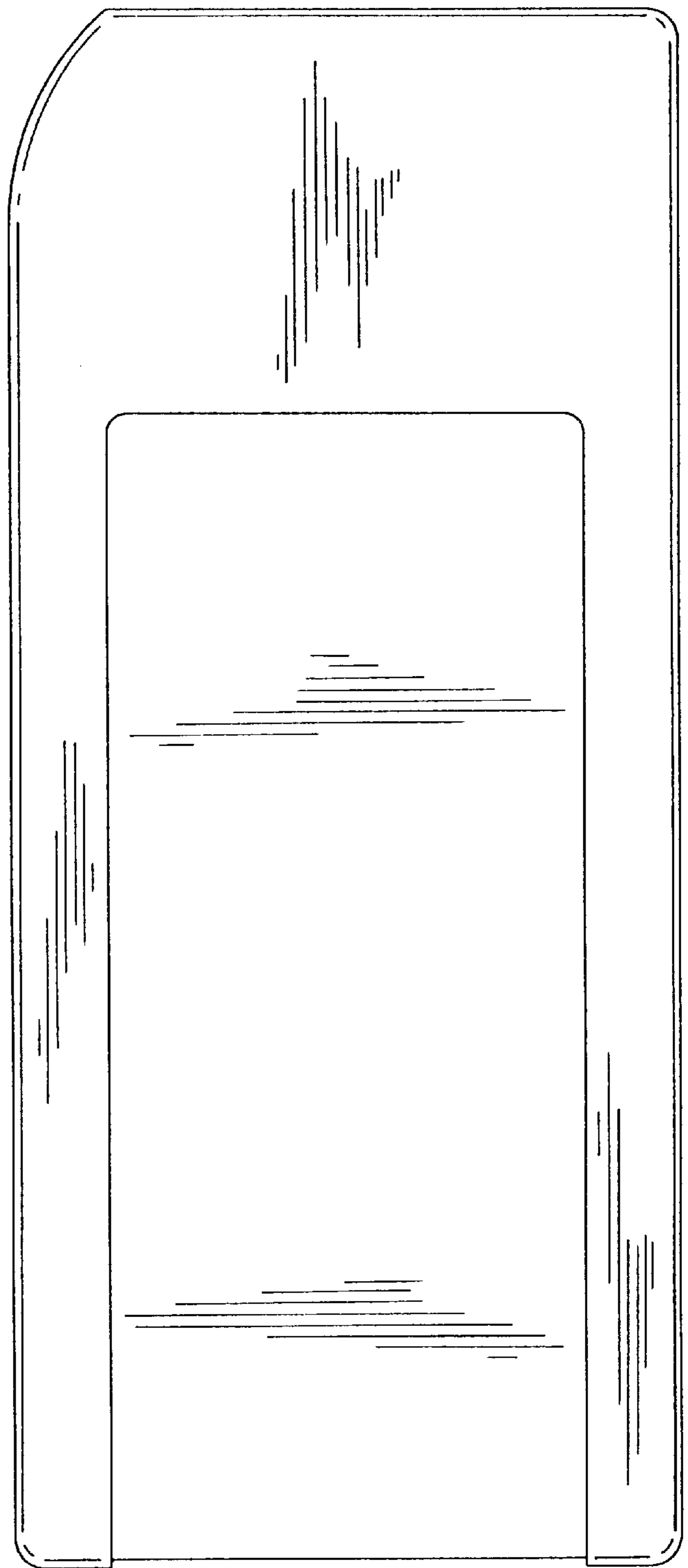


FIG. 6

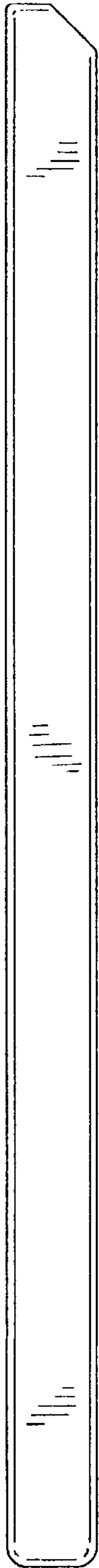


FIG. 7

